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(54) **MAGNETIC FIELD SENSOR WITH
MAGNETORESISTANCE ELEMENTS AND
CONDUCTIVE-TRACE MAGNETIC SOURCE**

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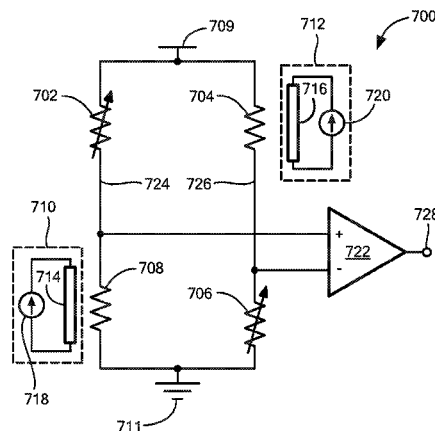
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(57) **ABSTRACT**

In an embodiment, a magnetic field sensor comprises a sub-
strate and a first magnetoresistive element supported by the
substrate. The magnetic field sensor also includes a second
magnetoresistive element supported by the substrate and
coupled in series with the first magnetoresistive element to
form a voltage node between the first and second magnetore-
sistive elements, and at which an output voltage is provided
that changes in response to an external magnetic field. The
magnetic field sensor also includes a magnetic source that
produces a local magnetic field having a strength sufficient to
bias the first magnetoresistive element to a resistive value that
is substantially resistant to changing in response to the exter-
nal magnetic field. In embodiments, additional magnetoresis-
tive elements are included to form an H-bridge circuit.

18 Claims, 6 Drawing Sheets



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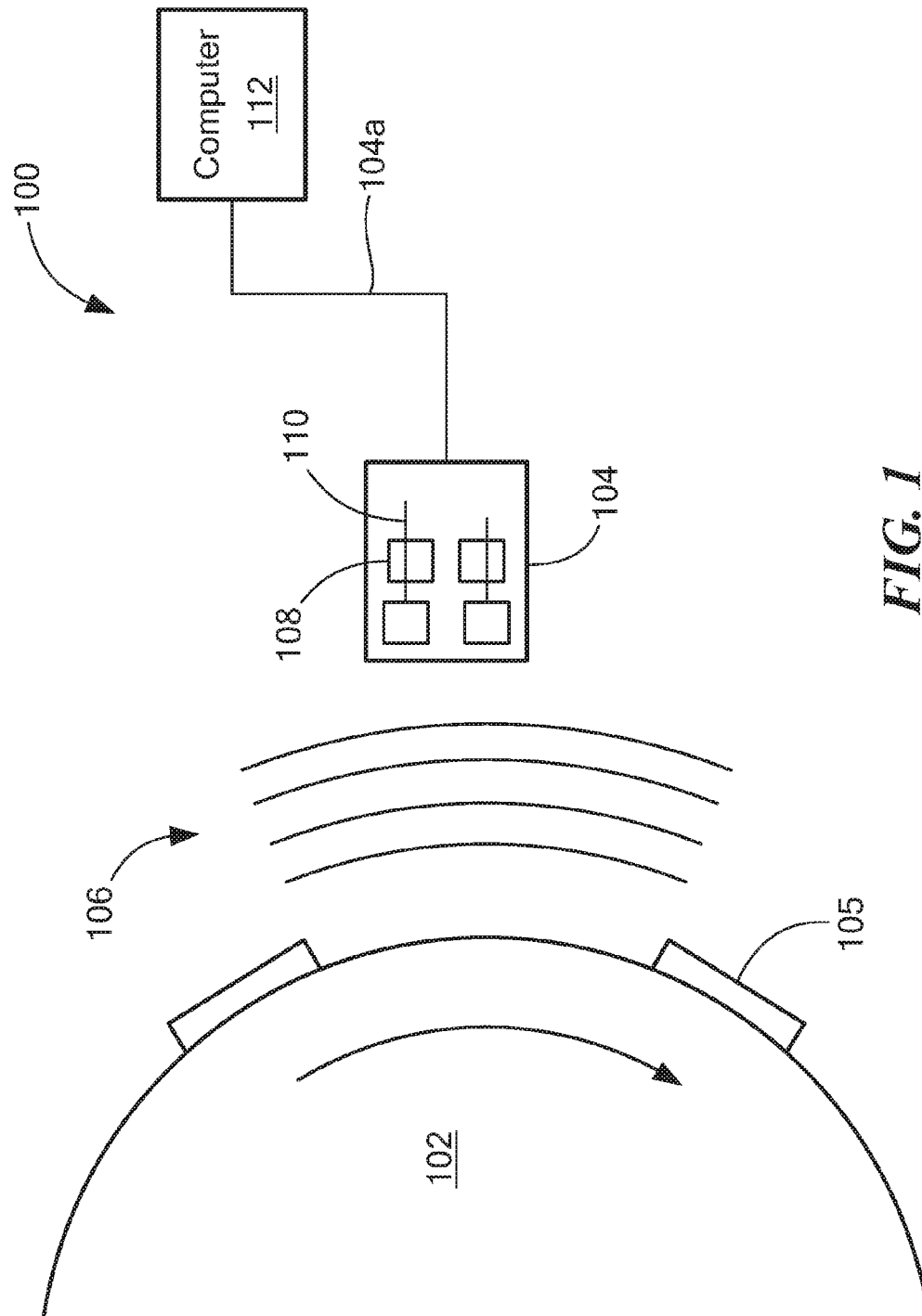


FIG. 1

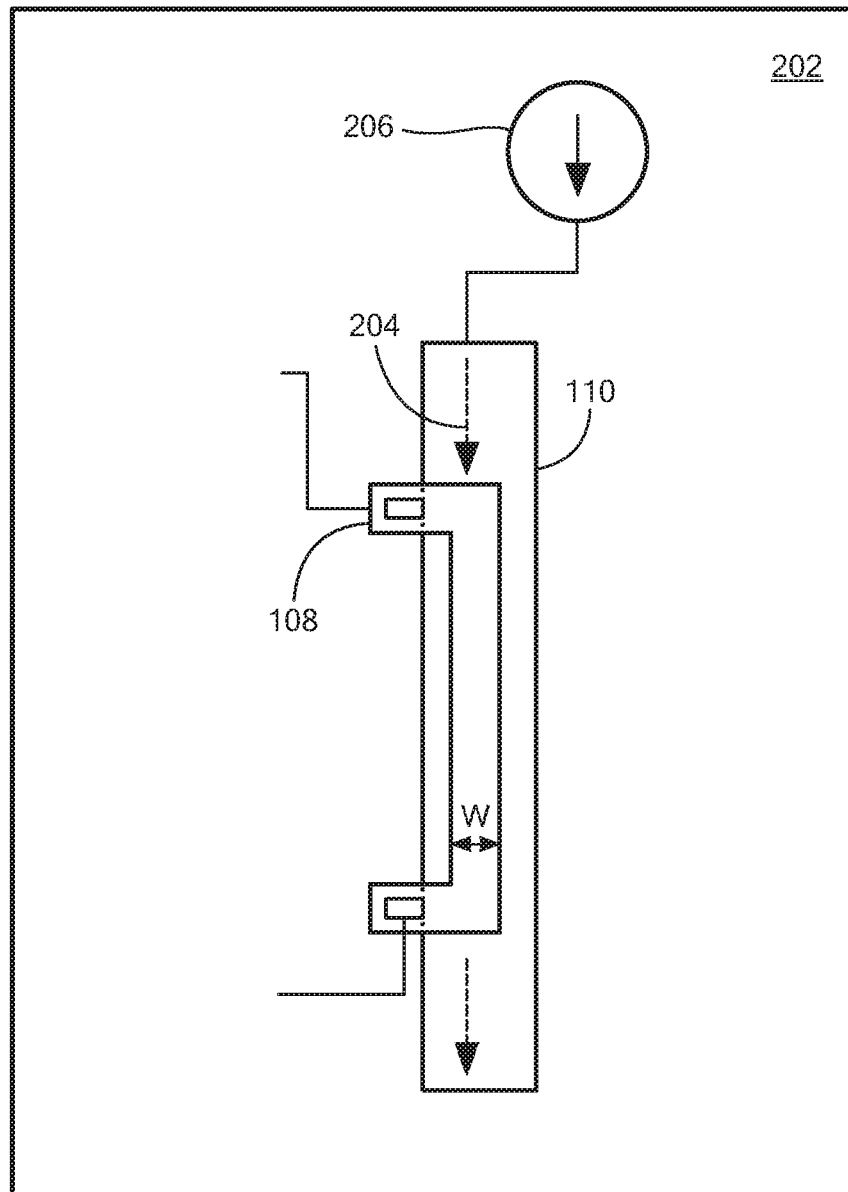


FIG. 2

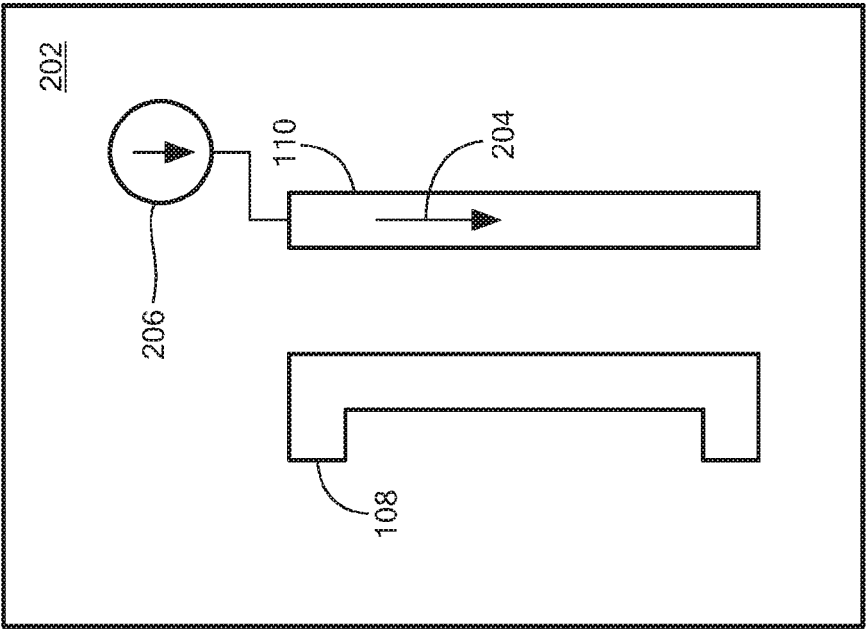


FIG. 3

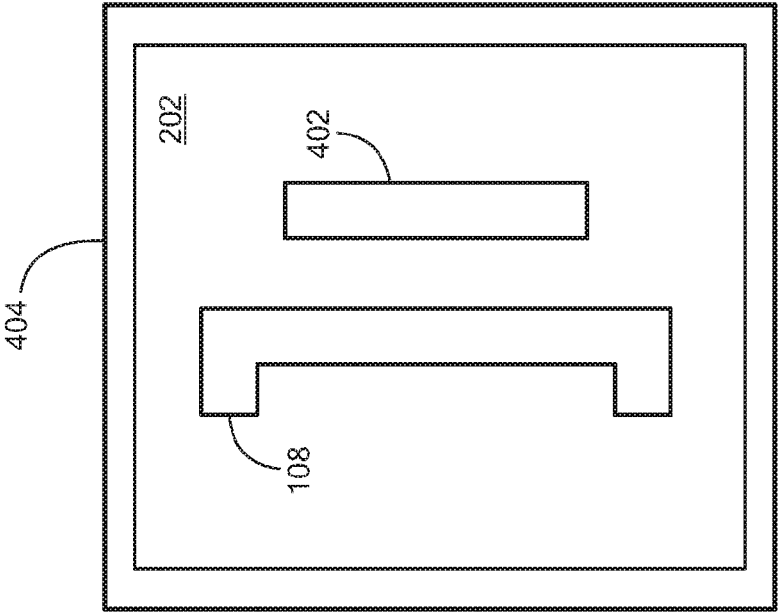


FIG. 4

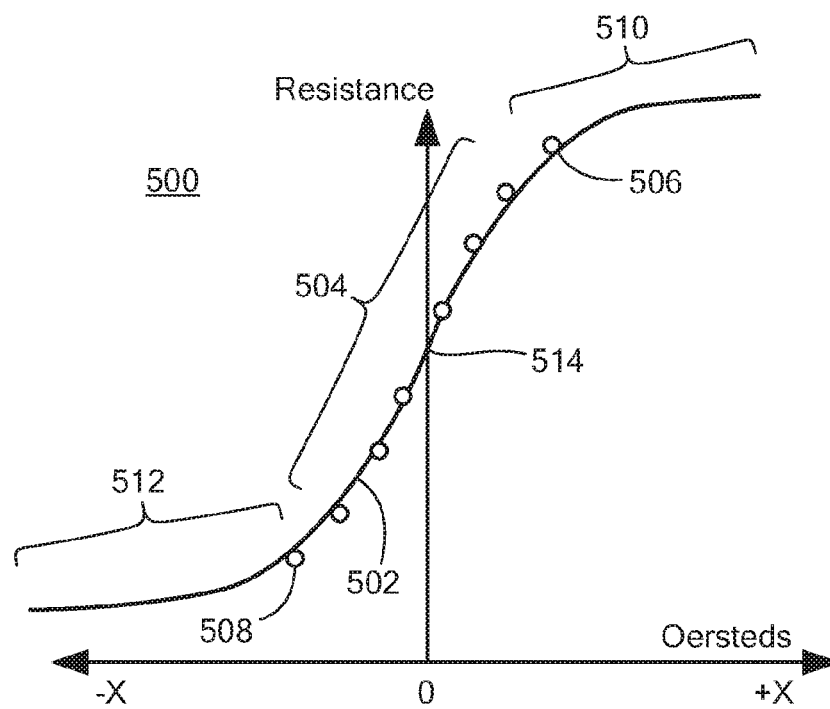


FIG. 5

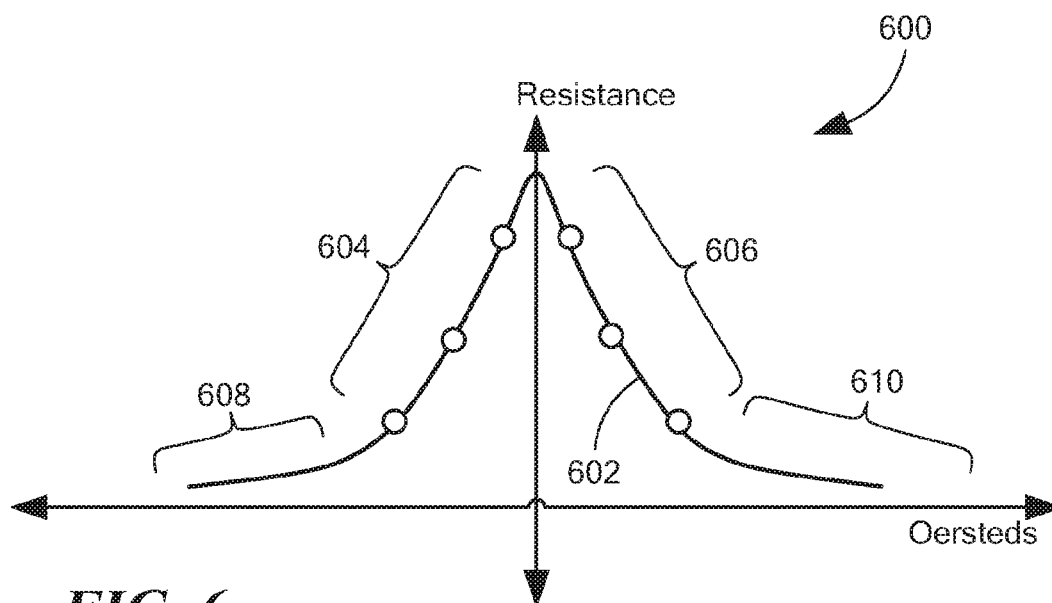
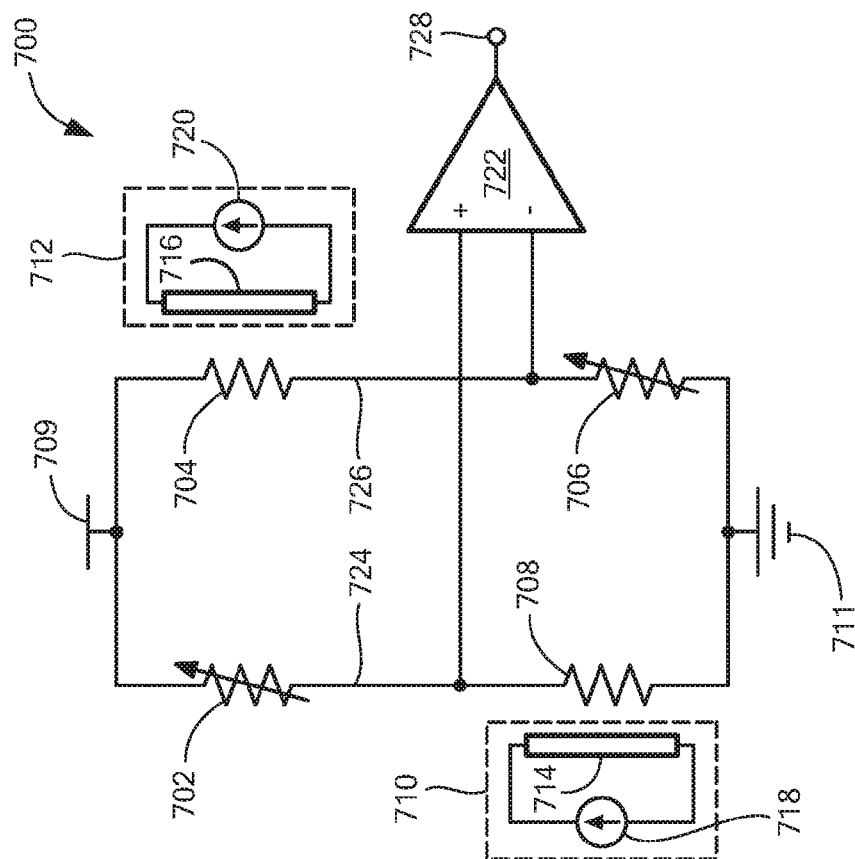
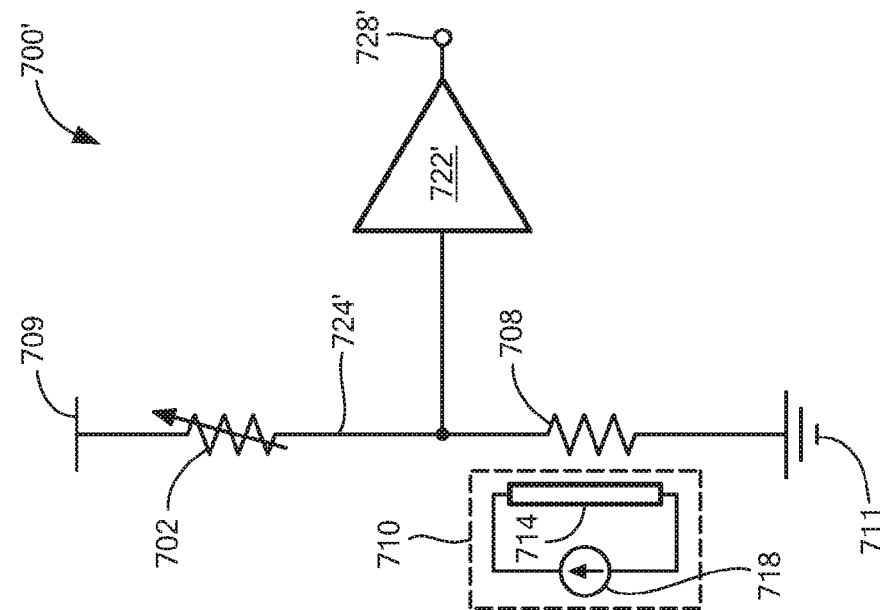


FIG. 6



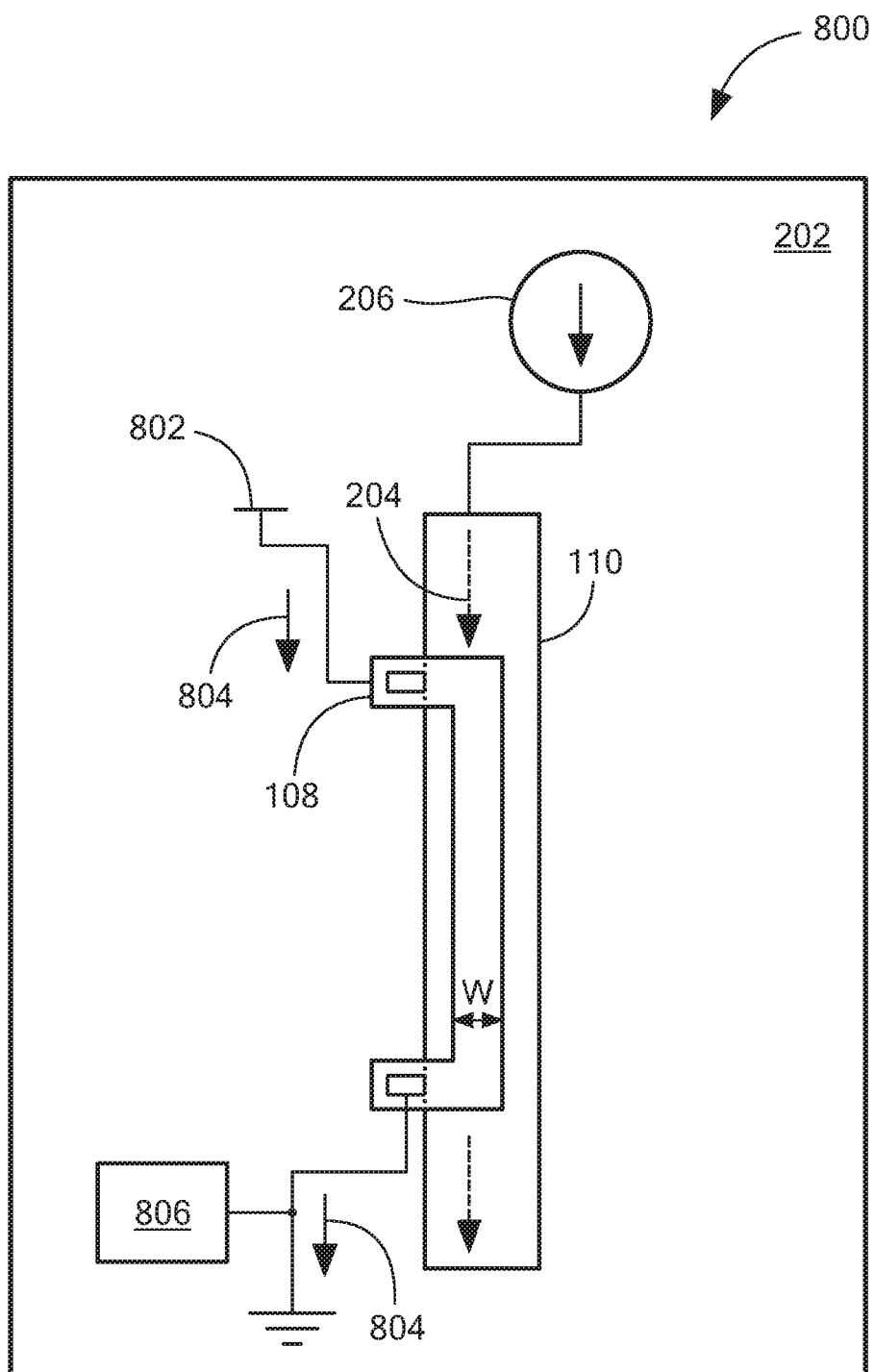


FIG. 8

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MAGNETIC FIELD SENSOR WITH MAGNETORESISTANCE ELEMENTS AND CONDUCTIVE-TRACE MAGNETIC SOURCE

FIELD OF THE INVENTION

This invention relates generally to magnetoresistance elements and, more particularly, to circuits having at least one magnetoresistive element biased by a magnetic source.

BACKGROUND

Changes in temperature can affect the way circuits operate. In environments where temperature can swing drastically, such as automotive or manufacturing environments, the circuit's operation can also change drastically. This can be problematic for circuits or applications that are particularly sensitive to temperature. For example, the accuracy of a sensor that operates in a motor vehicle may be compromised as the weather, or temperature of the engine, transmission, or brake system changes the temperature of the sensor.

Magnetic field sensors are used in many automotive and manufacturing environments. They may be used to detect the presence or motion of critical systems such as transmission systems, brakes, manufacturing robotic arms, etc. For example, a magnetic field sensor may count teeth on a rotating magnetic gear attached to a transmission shaft to determine speed or direction or may be attached to a brake system to determine whether to engage an automatic braking system. If changes in temperature compromise the accuracy of the magnetic field sensor, or otherwise affect performance of the magnetic field sensor, then the systems controlling the transmission or brake systems may also be affected.

SUMMARY

In an embodiment, a magnetic field sensor comprises a substrate and a first magnetoresistive element supported by the substrate. The magnetic field sensor also includes a second magnetoresistive element supported by the substrate and coupled in series with the first magnetoresistive element to form a voltage node between the first and second magnetoresistive elements, and at which an output voltage is provided that changes in response to an external magnetic field. The magnetic field sensor also includes a magnetic source that produces a local magnetic field having a strength sufficient to bias the first magnetoresistive element to a resistive value that is substantially resistant to changing in response to the external magnetic field. The first and second magnetoresistive elements may have a temperature coefficient that is substantially the same.

The magnetic field sensor also includes a third magnetoresistive element supported by the substrate. A fourth magnetoresistive element supported by the substrate and coupled in series with the third magnetoresistive element to form a second voltage node between the third and fourth magnetoresistive elements and at which an output voltage is provided that changes in response to the external magnetic field.

A first magnetic source is positioned adjacent to the first magnetoresistive element and produces a local magnetic field having a strength sufficient to bias the first magnetoresistive element to a resistive value that is substantially resistant to changing in response to the external magnetic field. A second magnetic source is positioned adjacent to the third magnetoresistive element and produces a second local magnetic field having strength sufficient to bias the third magnetoresistive element to a resistive value that is substantially resistant

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to changing in response to the external magnetic field. The first and second magnetoresistive elements have a temperature coefficient that is substantially the same and the third and fourth magnetoresistive elements have a temperature coefficient that is substantially the same, so that the magnetic field sensor produces an output between the first and second voltage nodes that is substantially invariant in response to changes of temperature.

BRIEF DESCRIPTION OF THE DRAWINGS

The foregoing features may be more fully understood from the following description of the drawings. The drawings aid in explaining and understanding the disclosed technology. Since it is often impractical or impossible to illustrate and describe every possible embodiment, the provided figures depict one or more exemplary embodiments. Accordingly, the figures are not intended to limit the scope of the invention. Like numbers in the figures denote like elements.

FIG. 1 is a block diagram of a system for detecting a magnetic target.

FIG. 2 shows a circuit that includes a magnetoresistive element supported by a substrate.

FIG. 3 shows another arrangement of a circuit that includes a magnetoresistive element supported by a substrate.

FIG. 4 shows a circuit that includes a magnetoresistive element and a magnet.

FIG. 5 is a graph of the resistive response of a type magnetoresistive element.

FIG. 6 is a graph of the resistive response of another type of magnetoresistive element.

FIG. 7 is a block diagram of a Wheatstone bridge circuit for detecting a magnetic field.

FIG. 7A is a block diagram of a resistor divider circuit for detecting a magnetic field.

FIG. 8 shows a circuit that includes a magnetoresistive element supported by a substrate.

DETAILED DESCRIPTION

As used herein, the term "magnetic field sensing element" is used to describe a variety of electronic elements that can sense a magnetic field. One such magnetic field sensing element is a magnetoresistance or magnetoresistive (MR) element. The magnetoresistance element has a resistance that changes in relation to a magnetic field experienced by the magnetoresistance element.

As is also known, there are different types of magnetoresistance elements, for example, a semiconductor magnetoresistance element such as Indium Antimonide (InSb), a giant magnetoresistance (GMR) element, for example, a spin valve, an anisotropic magnetoresistance element (AMR), a tunneling magnetoresistance (TMR) element, and a magnetic tunnel junction (MTJ). As used herein, the term "magnetoresistive element" may refer, without exclusivity, to any or all of these types of magnetoresistive elements. Depending on the device type and other application requirements, magnetoresistive elements may be a device made of a type IV semiconductor material such as Silicon (Si) or Germanium (Ge), or a type III-V semiconductor material like Gallium-Arsenide (GaAs) or an Indium compound, e.g., Indium-Antimonide (InSb).

The magnetoresistance element may be a single element or, alternatively, may include two or more magnetoresistance elements arranged in various configurations, e.g., a half bridge or full (Wheatstone) bridge.

As is known, magnetoresistance elements (e.g., GMR, TMR, AMR) tend to have axes of maximum sensitivity parallel to a substrate on which they are formed.

As used herein, the term “magnetic field sensor” is used to describe a circuit that uses a magnetic field sensing element, generally in combination with other circuits. Magnetic field sensors are used in a variety of applications, including, but not limited to, an angle sensor that senses an angle of a direction of a magnetic field, a current sensor that senses a magnetic field generated by a current carried by a current-carrying conductor, a magnetic switch that senses the proximity of a ferromagnetic object, a rotation detector that senses passing ferromagnetic articles, for example, magnetic domains of a ring magnet or a ferromagnetic target (e.g., gear teeth) where the magnetic field sensor may be used in combination with a back-biased or other magnet, and a magnetic field sensor that senses a magnetic field density of a magnetic field.

Various parameters characterize the performance of magnetic field sensors and magnetic field sensing elements. With regard to magnetic field sensing elements, the parameters include sensitivity, which is the change in the output signal of a magnetic field sensing element in response to a magnetic field, and linearity, which is the degree to which the output signal of a magnetic field sensor varies linearly (i.e., in direct proportion) to the magnetic field.

Giant magnetoresistance elements GMRs are known to have a relatively high sensitivity. GMRs are also known to have moderately good linearity, but over a restricted range of magnetic fields.

Referring now to the figures, FIG. 1 is a block diagram of a system 100 for detecting a target 102. System 100 includes a magnetic field sensor 104 placed adjacent to target 102 so that a magnetic field 106 can be sensed by magnetic field sensor 104. In an embodiment, target 102 is a magnetic target and produces magnetic field 106. In another embodiment, magnetic field 106 is generated by a magnetic source (e.g. a back-bias magnet or electromagnet) that is not coupled to target 102. In this instance, target 102 may be either a magnetic or a non-magnetic target. In these embodiments, as target 102 moves through or within magnetic field 106, it causes perturbations to magnetic field 106 that can be detected by magnetic field sensor 104.

Magnetic field sensor 104 may detect and process changes in magnetic field 106. For example, magnetic field sensor 104 may detect changes in magnetic field 106 as target 102 rotates and features 105 move closer to and away from magnetic field sensor 104, thus increasing and decreasing the strength of the magnetic field 106 experienced by magnetic field sensor 104. Magnetic field sensor 104 may also include circuitry to determine the speed, direction, proximity, angle, etc. of target 102 based on these changes to magnetic field 106.

In an embodiment, magnetic sensor 104 is coupled to a control unit, control circuit, engine control unit, or other similar computer 112, which may be a general purpose processor executing software or firmware, a custom processor, or an electronic circuit for processing output signal 104a from magnetic sensor 104. Output signal 104a may provide information about the speed and/or direction of target 102 to computer 112, which may then perform operations based on the received speed and direction. In an embodiment, computer 112 is an automotive computer (which may also be referred to as an engine control unit) installed in a vehicle and target 102 is a moving part within the vehicle, such as a transmission shaft, a brake rotor, etc. Magnetic sensor 104 detects the speed and/or direction of target 102 and computer

112 controls automotive functions (like all-wheel drive, ABS, speedometer display control, etc.) in response to the detected speed and direction.

In an embodiment, computer 112 may be located relatively distant from magnetic field sensor 104. For example, computer 112 may be located under the hood, in the cabin, or other location of a vehicle while magnetic field sensor 104 is located at a wheel or transmission element near the bottom of the vehicle. In such an embodiment, having a serial communication interface with a minimal number of electrical connections (e.g. wires) between computer 112 and magnetic field sensor 104 may be beneficial, and may reduce cost and maintenance requirements.

Referring to FIG. 2, a conductive trace (i.e. a conductive layer) 110 is supported by substrate 202. Substrate 202 may be a monocrystalline substrate or any other material substrate that can support integrated circuits. Substrate 202 may include various layers including, but not limited to, diffusion layers, implant layers, metal layers, via and contact layers, etc., that form integrated circuits supported by substrate 202.

Conductive trace 110 may be a metal layer, or any other type of conductive or semi-conductive trace that can carry a current 204. Although not shown, conductive trace 110 may comprise a plurality of conductive traces coupled in parallel. In an embodiment, current source 206 is an integrated circuit that supplies current 204. In another embodiment, current source 206 may be a circuit separate from substrate 202.

In embodiments, current source 206 is a variable, DC current source that can be programmed to produce current 204 in varying magnitudes. Current source 206 may also include circuitry to change the direction of current 204 flowing through conductive trace 110. In other embodiments, current source 206 is an AC current source, or a current source that produces current according to a predefined, oscillating pattern, such as a saw-tooth pattern, a square-wave pattern, a sine-wave pattern, etc. As known in the art, current flowing through conductive trace 110 will produce a magnetic field.

Magnetoresistive element 108 is also supported by substrate 202 and may comprise multiple layers including a pinned layer, a free layer, a non-fixed or sensing layer, a non-magnetic layer, and antiferromagnetic layer, a protective layer, etc. U.S. patent application Ser. No. 14/452,783 (filed Aug. 6, 2014 and incorporated here by reference) provides examples of some embodiments of magnetoresistive elements and their layers. Other constructions of the magnetoresistive elements are also possible and the techniques described herein are applicable to those magnetoresistive sensing elements as well. In embodiments, magnetoresistive element 108 may be formed as a giant-magnetoresistive element (“GMR”).

Magnetoresistive element 108 may be positioned adjacent to conductive trace 110 so that the magnetic field produced by current 204 can affect the resistance of magnetoresistive element 108. As shown in FIG. 2, magnetoresistive element 108 may be formed directly atop conductive trace 110 or conductive trace 110 may be formed directly atop magnetoresistive element 108. In other embodiments, magnetoresistive element 108 and conductive trace 110 may be on opposite sides of substrate 202. Magnetoresistive element 108 and conductive trace 110 may be separated by an insulating layer, such as an oxide, nitride, or polymer layer, or the like.

As known in the art, magnetoresistive elements are sensitive to magnetic fields. Specifically, the electrical resistance of the magnetoresistive element will change in the presence of a magnetic field. In an embodiment, the magnetic field

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produced by current **204** may have sufficient strength to bias magnetoresistive element **108** to a predetermined and/or constant value.

Referring to FIG. 3, in an embodiment, magnetoresistive element **108** is positioned adjacent to, but spaced from, conductive trace **110** on substrate **202**. With respect to conductive trace **110**, magnetoresistive element **108** may be positioned on the same side or on the opposite side of substrate **202**. Although separated, magnetoresistive element **108** and conductive trace **110** may be spaced so that the magnetic field produced by current **204** has sufficient strength to bias magnetoresistive element **108** to a predetermined resistive value.

As shown in FIG. 2 and FIG. 3, magnetoresistive element **108** and conductive trace **110** may be arranged substantially parallel to each other. In other embodiments, the elements may be perpendicular to each other or arranged at any other angle with respect to each other so long as the orientation allows the magnetic field produced by current **204** to bias magnetoresistive element **108** to a predetermined resistive value.

In certain embodiments, the width of conductive trace **110** may be greater than the width (labeled 'W') of magnetoresistive element **108**, as shown in FIG. 2. In other embodiments, the width of conductive trace **110** may be the same as or less than the width of magnetoresistive element **108**. In general, the respective widths of conductive trace **110** and magnetoresistive element **108** may be any widths that allow a magnetic field produced by a current flowing through conductive trace **110** to bias magnetoresistive element **108** to a predetermined resistive value.

Referring to FIG. 4, in another embodiment magnetoresistive element **108** is positioned adjacent to a permanent magnet **402** so that the magnetic field produced by magnet **402** has sufficient strength to bias magnetoresistive element **108** to a predetermined resistive value. Similarly to embodiments described above, magnetoresistive element **108** may be positioned adjacent to or atop magnet **402**, between magnet **402** and substrate **202**, or on the opposite side of substrate **202** with respect to magnet **402**. Also shown in FIG. 4 is a lead frame **404** which may carry signals from substrate **202** (i.e. from circuits supported by substrate **202**) to the outside of a chip package.

Like the conductive element **108** and magnetoresistive element **108** in FIGS. 2-3, magnetic **402** and conductive element **108** may be positioned atop each other, on opposite sides of substrate **202**, adjacent but separate from each other, etc., so long as the magnetic field produced by magnet **402** can bias the magnetoresistive element **108** to a predetermined resistive value.

Magnet **402** may be directly supported by substrate **202**, disposed on substrate **202**, or separate from substrate **202**. In the latter case, substrate **202** may be positioned within the same chip package as substrate **202** or on an outside surface of the chip package. Magnet **402** may also be mounted separately from the chip package on, for example, a frame or other mechanical structure. In embodiments, magnet **402** may be supported by, attached to, or otherwise disposed on or adjacent to substrate **202** and/or lead frame **404**, including on or adjacent to leads of a lead frame **404**.

As shown in FIG. 4, magnet **402** and conductive trace **110** may be arranged substantially parallel to each other. In other embodiments, the elements may be perpendicular to each other or arranged at any other angle with respect to each other so long as the orientation allows the magnetic field produced by magnet **402** to bias magnetoresistive element **108** to a predetermined resistive value.

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Referring to FIG. 5, a graph **500** has a horizontal axis representing the applied magnetic field (e.g. Oersteds, although in some cases this may be referred to as Gauss) produced by current **204** or magnet **402**, and a vertical axis representing resistance. The curve **502** represents the resistance of magnetoresistive element **108** as it is exposed to a magnetic field of varying strength.

Curve **502** is representative of a transfer function of an ideal GMR element, i.e., resistance versus magnetic field experienced by the GMR element. The transfer function **502** has a linear region **504** between an upper saturation point **506** and a lower saturation point **508**. Regions **510** and **512** are in saturation. In an embodiment, region **510** may correspond to a maximum resistance (maximum resistance range) of magnetoresistive element **108** and region **512** may correspond to a minimum resistance (or minimum resistance range) of magnetoresistive element **108**. It should be understood that the linear region **504** (and the saturation regions **510** and **512**) is an example of an ideal linear region (and ideal saturation regions) and the response of real magnetoresistive elements may vary. Also, curve **502** may be representative of a spin-valve type magnetoresistive element where the nominal value of the magnetoresistive element (i.e. the value when external magnetic field has zero strength) is a middle resistance point (i.e. a point **514** in the middle of curve), the maximum resistance or resistance range corresponds to a saturation region (i.e. saturation region **510**), and the minimum resistance or resistance range corresponds to another saturation region (i.e. saturation region **512**). In other words, when the magnetoresistive element is subjected to a sufficiently large (e.g. a field that is large or strong enough to saturate the magnetoresistance element in one direction) external magnetic field in a first direction, the resistance of the magnetoresistive element may increase to a maximum resistance value in saturation region **510**; when the magnetoresistive element is subjected to a sufficiently large external magnetic field in the opposite direction, the resistance of the magnetoresistive element may decrease to a minimum resistance value in saturation region **512**; and when the magnetoresistive element is subjected to no external magnetic field (e.g. a magnetic field with strength of about 0), the resistance of the magnetoresistive element may be a value between that of saturation region **510** and **512**, as shown by point **514** corresponding to a zero-strength external magnetic field.

Referring also to FIGS. 1-4, the local magnetic field produced by current **204** and/or magnet **402** may bias magnetoresistive element **108** so that it is in saturation region **510** or **512**. Because curve **502** flattens in these saturation regions, the resistance of magnetoresistive element **108** will remain relatively constant in the presence of changes in an external magnetic field, such as magnetic field **106**. Stated differently, in the saturation regions, magnetoresistive element **108** is substantially resistant to changing in response to an external magnetic field.

As magnetic field sensor **104** operates, external perturbations in the magnetic field experienced by magnetoresistive element **108** (for example caused by the rotation of target **102**) are typically small in relation to the magnetic field produced by current **204** or magnet **402** as experienced by magnetoresistive element **108**. This may be due, at least in part, to the close proximity of magnetoresistive element **108** to current **204** or magnet **402**. Thus, because magnetoresistive element **108** is held in saturation by current **204** or magnet **402**, these external perturbations may have little or no effect on the resistance of magnetoresistive element **108**. By placing magnetoresistive element **108** into the saturation region **510** or **512**, the magnetic field generated by current **204** or magnet

402 can bias magnetoresistive element 108 to a predetermined, relatively constant resistive value in the presence of other, external magnetic fields. In other embodiments, the magnet may be positioned on a lead-frame of the magnetic field sensor, as described, for example, in U.S. Pat. No. 7,358, 724 and/or U.S. Publication No. 2013/0249544, which are both incorporated here by reference.

Referring to FIG. 6, a graph 600 has a horizontal axis representing the strength (e.g. Oersteds) of the magnetic field that may be produced by current 204 or magnet 402, and a vertical axis representing resistance. The curve 602 represents the resistance of magnetoresistive element 108 as it is exposed to a magnetic field of varying strength.

The arrangement and orientation of the ferromagnetic and non-ferromagnetic layers of a GMR can affect the way a GMR element responds to an external magnetic field. Different orientations of these layers can produce different types of GMR elements. Thus, curve 602 is representative of an ideal transfer function of another type of GMR element, i.e., resistance versus magnetic field experienced by the GMR element. The transfer function 602 has linear regions 604 and 606 and saturation regions 608 and 610. It should be understood that the linear regions 604 and 606 are examples of ideal linear regions. Curve 602 represents a magnetoresistive element that has a relatively high resistance when exposed to a lower-strength magnetic field and a relatively low resistance when exposed to a higher-strength magnetic field. Although not shown, some magnetoresistive elements have a transfer function that is the inverse of curve 602—i.e. a transfer function shaped like a “V.” These magnetoresistive elements have a relatively low resistance when exposed to a lower-strength magnetic field and a relatively high resistance when exposed to a higher-strength magnetic field. A magnetoresistive element with any of these transfer functions, or with any other shape transfer function, may be used so long as the magnetoresistive element can be biased to a predetermined resistive value and/or placed in saturation.

Referring now to FIG. 7, a circuit 700 includes four magnetoresistive elements 702, 704, 706, and 708 arranged in a bridge configuration (also referred to as a Wheatstone bridge) and coupled to voltage source 709 and ground reference 711. Magnetoresistive elements 702, 704, 706, and 708 may be the same as or similar to magnetoresistive element 108 in the previous figures.

In an embodiment, magnetoresistive element 708 is positioned adjacent to magnetic source 710, and magnetoresistive element 704 is placed adjacent to magnetic source 712. Magnetic sources 710 and 712 may include a conductive trace 714 and 716, respectively, and a current source 718 and 720, respectively. Conductive trace 714 may be coupled to current source 718, and conductive trace 716 may be coupled to current source 720, to form circuits that produce magnetic fields, as described above. In embodiments, conductive traces 714 and 716 are the same as or similar to conductive trace 110 (e.g. FIGS. 2 and/or 3) and current sources 718 and 720 are the same as or similar to current source 206 (e.g. FIGS. 2 and/or 3). In other embodiments, conductive trace 110 may be a wire, a coil, or any other conductor that can produce a magnetic field when a current runs through the conductor.

It is not a requirement that magnetic sources 710 and 712 include conductive traces and current sources as shown in FIG. 7. As described above, the magnetic source may comprise a permanent magnet (e.g. magnet 402 in FIG. 4), or any other type of circuit or material that can produce a local magnetic field with sufficient strength to bias magnetoresistive elements 704 and 708 to a predetermined resistive value. In an embodiment, the magnetic field may be produced by a

permanent magnet (such as a magnet from a rare earth material such as samarium cobalt (“SmCo”) or from ferrite magnetic material for example), positioned on a lead from of the magnetic field sensor. The local magnetic field may have a strength or shape directed at magnetoresistive element 704 and 708 so that the local magnetic field biases the magnetoresistive element, but does not substantially affect other elements, circuits, or systems nearby.

In an embodiment, circuit 700 also includes a differential amplifier 722 having its positive terminal coupled to signal 724 (i.e. the voltage node between magnetoresistive elements 702 and 708), and its negative terminal coupled to signal 726 (i.e. the voltage node between magnetoresistive elements 704 and 706). Thus, output signal 728 represents the voltage difference between voltage nodes 724 and 726.

Referring also to FIG. 1, magnetic field sensor 104 may include a bridge (e.g. a Wheatstone bridge) circuit the same as or similar to circuit 700. In operation, as target 102 moves or rotates, bridge circuit 700 detects changes in magnetic field 106 caused by the motion of target 102.

Magnetoresistive elements 702 and 708 form a voltage divider circuit having voltage node 724 as the output. Magnetic source 710 may bias magnetoresistive element 708 to a predetermined value. In an embodiment, magnetoresistive element 708 is biased to saturation so that its resistance stays substantially constant in response to changes in external magnetic field 106. Because magnetoresistive element 702 is not placed adjacent to a magnetic biasing source such as 710 or 712, changes in external magnetic field 106 cause the resistance of magnetoresistive element 702 to change. As the resistance of magnetoresistive element 702 changes in response to external magnetic field 106, the voltage at node 724 changes.

Similarly, magnetoresistive elements 704 and 706 form a voltage divider circuit having voltage node 726 as the output. Magnetic source 712 may bias magnetoresistive element 704 to a predetermined value. In an embodiment, magnetoresistive element 704 is biased to saturation so that its resistance stays substantially constant in response to changes in external magnetic field 106. Because magnetoresistive element 706 is not placed adjacent to a magnetic biasing source such as 710 or 712, changes in external magnetic field 106 cause the resistance of magnetoresistive element 706 to change. As the resistance of magnetoresistive element 706 changes in response to external magnetic field 106, the voltage at node 726 changes.

Because magnetoresistive element 702 is at the top of its resistor divider circuit and magnetoresistive element 706 is at the bottom of its resistor divider circuit, and assuming that magnetoresistive elements 702-708 are the same type of magnetoresistive elements, the changes of voltage at nodes 724 and 726 will be opposite to each other in response to changes in magnetic field 106. For example, if the strength of magnetic field 106 increases, the resistance of magnetoresistive elements 702 and 706 may increase, causing the voltage at node 724 to decrease and the voltage at node 726 to increase. Differential amplifier 722 receives the voltages at nodes 724 and 726 as inputs and provides output signal 728, which may be an amplified signal representing the voltage difference between nodes 724 and 726.

As known in the art, many electronic components respond to changes in temperature. Electronic components have a temperature coefficient, which may be a scalar or function that describes how the component behaves over a range of temperatures. The temperature coefficient of a magnetoresistive element is generally a function of the material and geometry of the magnetoresistive element, as well as other factors.

In an embodiment, magnetoresistive elements **704** and **708** are the same type of magnetoresistive element, and may be formed from the same fabrication process, and contain substantially the same material and dimensions. Thus, magnetoresistive elements **704** and **708** may have substantially the same temperature coefficient and substantially the same response to temperature.

Magnetoresistive elements **702** and **706** may also be of the same type, be formed from the same fabrication process, and have the same materials and dimensions as each other, and thus have substantially the same temperature coefficient as each other. In an embodiment, all four magnetoresistive elements **702-708** are the same type, are formed from the same fabrication process, and have the same materials and dimensions as each other, and thus have substantially the same temperature coefficient. In these embodiments, the output of bridge circuit **700** may not be substantially affected by changes in temperature.

Considering an example where magnetic field sensor **104** (and bridge circuit **700**) are part of an automotive system, changes in temperature due to weather, or heat from the engine, brakes, or transmission can expose magnetic field sensor **104** to drastic temperature swings. However, if magnetoresistive elements **702-708** are substantially the same, the voltages at nodes **724** and **726** may remain substantially invariant with respect to changes in temperature because each of the magnetoresistive elements **702-708** will have the same or a similar temperature coefficient, and will have substantially the same response to temperature.

Referring now to FIG. 7A, a circuit **700'** is a resistor divider circuit for detecting a magnetic field. Circuit **700'** include two magnetoresistive elements **702** and **708**. Magnetoresistive element **702** may be coupled to voltage source **709** and magnetoresistive element **708** may be coupled to ground reference **711**. Magnetoresistive elements **702** and **708** may be the same as or similar to magnetoresistive element **108** in the previous figures.

In an embodiment, magnetoresistive element **708** is positioned adjacent to magnetic source **710**. Magnetic source **710** may include a conductive trace **714** and a current source **718**. Conductive trace **714** may be coupled to current source **718** to form a circuit that produces a magnetic field, as described above. In embodiments, conductive trace **714** is the same as or similar to conductive trace **110** (e.g. FIGS. 2 and/or 3) and current source **718** is the same as or similar to current source **206** (e.g. FIGS. 2 and/or 3). In other embodiments, conductive trace **714** may be a wire, a coil, or any other conductor that can produce a magnetic field when a current runs through the conductor.

It is not a requirement that magnetic source **710** includes conductive traces and current sources as shown in FIG. 7A. As described above, the magnetic source may comprise a permanent magnet (e.g. magnet **402** in FIG. 4), or any other type of circuit or material that can produce a local magnetic field with sufficient strength to bias magnetoresistive element **708** to a predetermined resistive value. The local magnetic field may have a strength or shape directed at magnetoresistive element **708** so that the local magnetic field biases the magnetoresistive element, but does not substantially affect other elements, circuits, or systems nearby.

In an embodiment, circuit **700'** also includes an amplifier **722'** coupled to signal **724'** (i.e. the voltage node between magnetoresistive elements **702** and **708**). Thus, output signal **728'** represents the voltage at voltage node **724'**.

Referring also to FIG. 1, magnetic field sensor **104** may include one or more resistor divider circuits the same as or similar to circuit **700'**. In operation, as target **102** moves or

rotates, circuit **700'** detects changes in magnetic field **106** caused by the motion of target **102**.

Magnetoresistive elements **702** and **708** form a voltage divider circuit having voltage node **724** as the output. Magnetic source **710** may bias magnetoresistive element **708** to a predetermined value. In an embodiment, magnetoresistive element **708** is biased to saturation so that its resistance stays substantially constant in response to changes in external magnetic field **106**. Because magnetoresistive element **702** is not placed adjacent to a magnetic biasing source such as **710**, changes in external magnetic field **106** cause the resistance of magnetoresistive element **702** to change. As the resistance of magnetoresistive element **702** changes in response to external magnetic field **106**, the voltage at node **724'** changes.

Because magnetoresistive element **702** is at the top of its resistor divider circuit, and assuming that magnetoresistive elements **702** and **708** are the same type of magnetoresistive elements, the changes of voltage at node **724'** will be proportional to changes in the strength or flux of magnetic field **106**. For example, if the strength of magnetic field **106** increases, the resistance of magnetoresistive elements **702** may increase, causing the voltage at node **724'** to decrease. Amplifier **722'** receives the voltages at node **724'** as an input and provides output signal **728'**, which may be an amplified signal representing the voltage at node **724'**.

In another embodiment, resistor divider **700'** may be arranged so that magnetic source **710** is positioned adjacent to magnetoresistive element **702** rather than adjacent to magnetoresistive element **708** (not shown). In such an embodiment, the top portion of resistor divider circuit **700'** (comprising magnetoresistive element **702**) may have a resistance that is substantially invariant to changes in external magnetic field **106** and the bottom portion of resistor divider circuit **700'** (comprising magnetoresistive element **708**) may have a resistance that changes in response to changes in external magnetic field **106**. Like the example above, in this embodiment, the voltage at node **724'** will also change with respect to changes in external magnetic field **106**.

Referring now to FIG. 8, conductive trace **110** and magnetoresistive element **108** may be used to form a current reference circuit **800**. Similarly to embodiments described above, magnetoresistive element **108** may be placed adjacent to conductive trace **110** so that a magnetic field produced by current **204** can bias magnetoresistive element **108** to a predetermined resistive value. Current reference circuit **800** also includes a constant, DC voltage source **802** coupled to magnetoresistive element **108**. Current reference circuit **800** may also include a current measuring circuit **806**, such as a current mirror circuit for example, to measure the current **804** flowing through magnetoresistive element **108**.

In operation, the magnetic field produced by current **204** will bias magnetoresistive element **108** to a predetermined resistive value. In an embodiment, magnetoresistive element **108** will be biased to saturation, as described above, so that the resistance of magnetoresistive element **108** is relatively constant in the presence of external magnetic fields. As noted above, the magnetic field may also be produced by a permanent magnet positioned adjacent to magnetoresistive element, such as on a lead frame of the magnetic field sensor, for example.

Voltage source **802** may provide a constant voltage across magnetoresistive element **108**, which may drive current **804** through magnetoresistive element **108**. One skilled in the art will recognize that, in this configuration, current **804** may be defined as V_s/R_m , where V_s is the voltage across magnetore-

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sistive element and R_m is the resistance of magnetoresistive element **108** in the presence of the magnetic field produced by current **204**.

As noted above, the resistance of magnetoresistive element **108** may be affected by temperature according to the temperature coefficient of the magnetoresistive element. Therefore, as the temperature changes, the resistance R_m and the current **804** may also change. In other words, as a change in temperature occurs, a corresponding change in the magnitude of current **804** may occur. These changes in current can be detected by current measuring circuit **806** and used to determine the temperature coefficient of magnetoresistive element **108**, to measure the external temperature, etc.

Having described preferred embodiments, which serve to illustrate various concepts, structures and techniques, which are the subject of this patent, it will now become apparent that other embodiments incorporating these concepts, structures and techniques may be used. Accordingly, it is submitted that that scope of the patent should not be limited to the described embodiments but rather should be limited only by the spirit and scope of the following claims.

The invention claimed is:

1. A magnetic field sensor comprising:
a substrate;
a first magnetoresistive element supported by the substrate;
a second magnetoresistive element supported by the substrate and coupled in series with the first magnetoresistive element to form a voltage node between the first and second magnetoresistive elements and at which an output voltage is provided that changes in response to an external magnetic field; and
a magnetic source producing a local magnetic field having a strength sufficient to bias the first magnetoresistive element to a resistive value that is substantially resistant to changing in response to the external magnetic field;
wherein the magnetic source comprises a conductive trace supported by the substrate and configured to carry a current to provide the local magnetic field.
2. The magnetic field sensor of claim 1 wherein the first and second magnetoresistive elements have a temperature coefficient that is substantially the same.
3. The magnetic field sensor of claim 1 further comprising:
a third magnetoresistive element supported by the substrate;
a fourth magnetoresistive element supported by the substrate and coupled in series with the third magnetoresistive element to form a second voltage node between the third and fourth magnetoresistive elements and at which an output voltage is provided that changes in response to an external magnetic field; and
a magnetic source producing a second local magnetic field having a strength sufficient to bias the third magnetoresistive element to a resistive value that is substantially resistant to changing in response to the external magnetic field.
4. The magnetic field sensor of claim 3 wherein the first, second, third, and fourth magnetoresistive elements form a bridge circuit.
5. The magnetic field sensor of claim 1 wherein the first and second magnetoresistive elements comprise giant-magnetoresistive elements, TMR elements, AMR elements, MTJ elements, and/or spin valve elements.
6. The magnetic field sensor of claim 1 wherein the first magnetoresistive element is disposed adjacent to the conductive trace.

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7. The magnetic field sensor of claim 6 wherein the conductive trace is disposed atop the first magnetoresistive element.

8. The magnetic field sensor of claim 1 wherein the first magnetoresistive element is disposed on the substrate so it is not in direct contact with the conductive trace.

9. The magnetic field sensor of claim 8 further comprising an oxide, nitride, and/or polymer layer disposed between the first magnetoresistive element and the conductive trace.

10. The magnetic field sensor of claim 1 further comprising a current source to provide the current, wherein the current source is capable of switching a direction of flow of the current to control the resistive value of the first magnetoresistive element.

11. The magnetic field sensor of claim 1 further comprising a current source to provide the current, wherein the current source is a variable current source capable of varying a magnitude of the current to control the resistive value of the first magnetoresistive element.

12. The magnetic field sensor of claim 1 wherein the first magnetoresistive element is arranged substantially parallel to the conductive trace.

13. The magnetic field sensor of claim 1 wherein the substrate comprises an integrated circuit.

14. The magnetic field sensor of claim 1 further comprising a circuit to measure a voltage across at least one of the magnetoresistive elements to detect the external magnetic field.

15. The magnetic field sensor of claim 1 wherein the first and second magnetoresistive elements comprise spin-valves.

16. The magnetic field sensor of claim 1 wherein the resistive value corresponds to a maximum resistance or a minimum resistance of the first magnetoresistive element.

17. The magnetic field sensor of claim 1 wherein the resistive value corresponds to a saturation resistance of the first magnetoresistive element.

18. A magnetic field sensor comprising:

- a substrate;
 - first magnetoresistive element supported by the substrate;
 - a second magnetoresistive element supported by the substrate and coupled in series with the first magnetoresistive element to form a first voltage node between the first and second magnetoresistive elements at which an output voltage is provided that changes in response to an external magnetic field; and
 - a third magnetoresistive element supported by the substrate;
 - a fourth magnetoresistive element supported by the substrate and coupled in series with the third magnetoresistive element to form a second voltage node between the third and fourth magnetoresistive elements and at which an output voltage is provided that changes in response to the external magnetic field;
 - a first magnetic source positioned adjacent to the first magnetoresistive element and producing a first local magnetic field having a strength sufficient to bias the first magnetoresistive element to a resistive value that is substantially resistant to changing in response to the external magnetic field; and
 - a second magnetic source positioned adjacent to the third magnetoresistive element and producing a second local magnetic field having strength sufficient to bias the third magnetoresistive element to a resistive value that is substantially resistant to changing in response to the external magnetic field;
- wherein the first and second magnetoresistive elements have a temperature coefficient that is substantially the same and the third and fourth magnetoresistive elements

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have a temperature coefficient that is substantially the same, so that the magnetic field sensor produces an output between the first and second voltage nodes that is substantially invariant in response to changes of temperature;
wherein the first and second magnetic sources comprise conductive traces supported by the substrate and configured to carry current to provide the respective first and second local magnetic fields.

* * * * *

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UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 9,322,887 B1
APPLICATION NO. : 14/556523
DATED : April 26, 2016
INVENTOR(S) : Jeffrey Eagen et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In the Specification

Column 1, line 54 delete “element supported” and replace with --element is supported--.

Column 2, line 29-30 delete “type magnetoresistive” and replace with --type of magnetoresistive--.

Column 5, line 45 delete “, magnetic 402” and replace with --magnet 402--.

Column 6, line 42 delete “ration” and replace with --regions--.

Column 8, line 3 delete “lead from of the” and replace with --lead frame of the--.

Column 8, line 5 delete “element” and replace with --elements--.

Column 9, line 31 delete “include” and replace with --includes--.

Column 10, line 21 delete “elements” and replace with --element--.

Column 10, line 60 delete “magnetoresistive element,” and replace with --magnetoresistive element 108,--.

Column 11, line 1 delete “element” and replace with --element 108--.

Column 11, line 18-19 delete “that that” and replace with --that the--.

Signed and Sealed this
Twentieth Day of September, 2016



Michelle K. Lee
Director of the United States Patent and Trademark Office